

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No.09/468,247
 Priority Filing Date12/20/99
 Inventor.....Perino et al.
 Applicant Rambus, Inc.
 Priority Group Art Unit2833
 Priority Examiner Paumen
 Attorney's Docket No. RB1-035USC3
 Title: Chip Socket Assembly and Chip File Assembly for Semiconductor Chips

PRELIMINARY AMENDMENT

To: Commissioner of Patents and Trademarks,
Washington, D.C. 20231

From: Daniel L. Hayes (Tel. 509-324-9256; Fax 509-323-8979)
Customer No. 29501



29150

PATENT & TRADEMARK OFFICE

AMENDMENTS**In the Specification:**

On page 2, prior to the heading "FIELD OF THE INVENTION", please
insert the following:

--RELATED APPLICATIONS

This is a continuation of U.S. Patent Application Serial No. 09/468,247,
filed December 20, 1999, which is now U.S. Patent No.--

In the Claims:

Please cancel claims 1-67.

Please add the following new claims 68-90.

1 **68.** A chip package comprising:

2 packaging material having a first side and a second side,

3 a lead extending from the first side of the packaging material, and

4 a first clip portion extending from a second side of the packaging material.

5
6 **69.** The chip package of claim 68, further comprising a second clip
7 portion extending from a third side of the packaging material.

8
9 **70.** The chip package of claim 69, further comprising a flexible insert
10 residing between the lead and the first side of the packaging material, wherein the
11 flexible insert supplies spring force when the lead is compressed.

12
13 **71.** The chip package of claim 70, wherein the flexible insert is
14 cylindrical.

15
16 **72.** The chip package of claim 71, wherein the flexible insert is a
17 compliant material.

18
19 **73.** The chip package of claim 72, wherein the compliant material is an
20 elastomer.

21
22 **74.** The chip package of claim 70, wherein the lead is substantially C-
23 shaped.

1 **75.** The chip package of claim 74, wherein the lead is compressible.

2
3 **76.** The chip package of claim 70, wherein the lead is compressible.

4
5 **77.** The chip package of claim 68, further comprising a support pin
6 extending from the packaging material.

7
8 **78.** The chip package of claim 69, wherein the first and second clip
9 portions are integral with the packaging material.

10
11 **79.** The chip package of claim 68, wherein the lead is a flexible metallic
12 material.

13
14 **80.** The chip package of claim 78, wherein the metallic material
15 comprises beryllium-copper.

16
17 **81.** The chip package of claim 68, wherein the packaging material is
18 comprised of a flexible material.

19
20 **82.** The chip package of claim 81, wherein the flexible material supplies
21 spring force when the lead is compressed.

22
23 **83.** The chip package of claim 68, wherein the packaging material
24 comprises silicone rubber.

1 **84.** The chip package of claim 68, further comprising a cam follower
2 extending from the packaging material.

3
4 **85.** The chip package of claim 68, further comprising an integrated
5 circuit disposed in the packaging material.

6
7 **86.** The chip package of claim 69, wherein the first and second clip
8 portions are flexible.

9
10 **87.** The chip package of claim 68, wherein the packaging material has a
11 bottom-facing housing that extends laterally from the packaging material, the
12 bottom-facing housing having a pocket formed therein.

13
14 **88.** The chip package of claim 87, wherein an end of the lead is disposed
15 within
16 the pocket when the lead is compressed.

17
18 **89.** A package, comprising:
19 an integrated circuit enclosed with the package,
20 substantially C-shaped leads at a first end of the package,
21 a guide member on a side of the package, wherein the guide member has a
22 ramp, and
23 mechanical support pins at a second end of the package opposite the first
24 end,
25

1 wherein the package resides substantially horizontally with respect to a
2 circuit board when the package is inserted in a base assembly coupled to the circuit
3 board.
4

5 **90.** The package of claim 89, wherein the integrated circuit is a dynamic
6 random access memory device.
7

8
9
10 Respectfully Submitted,

11
12 Date: 9/20/01

13 By: Daniel L. Hayes
14 Daniel L. Hayes
15 Reg. No. 34,618
16
17
18
19
20
21
22
23
24
25